

SOT2040-1

HLSON6, thermal enhanced low profile small outline package, no leads, 6 terminals, 1.3 mm pitch, 4.5 mm x 4.0 mm x 1.2 mm body

29 August 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLSON6
Package style descriptive code	HLSON (thermal enhanced low profile small outline; no leads)
Mounting method type	S (surface mount)
Issue date	01-08-2019
Manufacturer package code	98ASA01496D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4.5	-	mm
package width	-	4	-	mm
seated height	-	1.2	-	mm
nominal pitch	-	1.3	-	mm
actual quantity of termination	-	6	-	



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2 Package outline

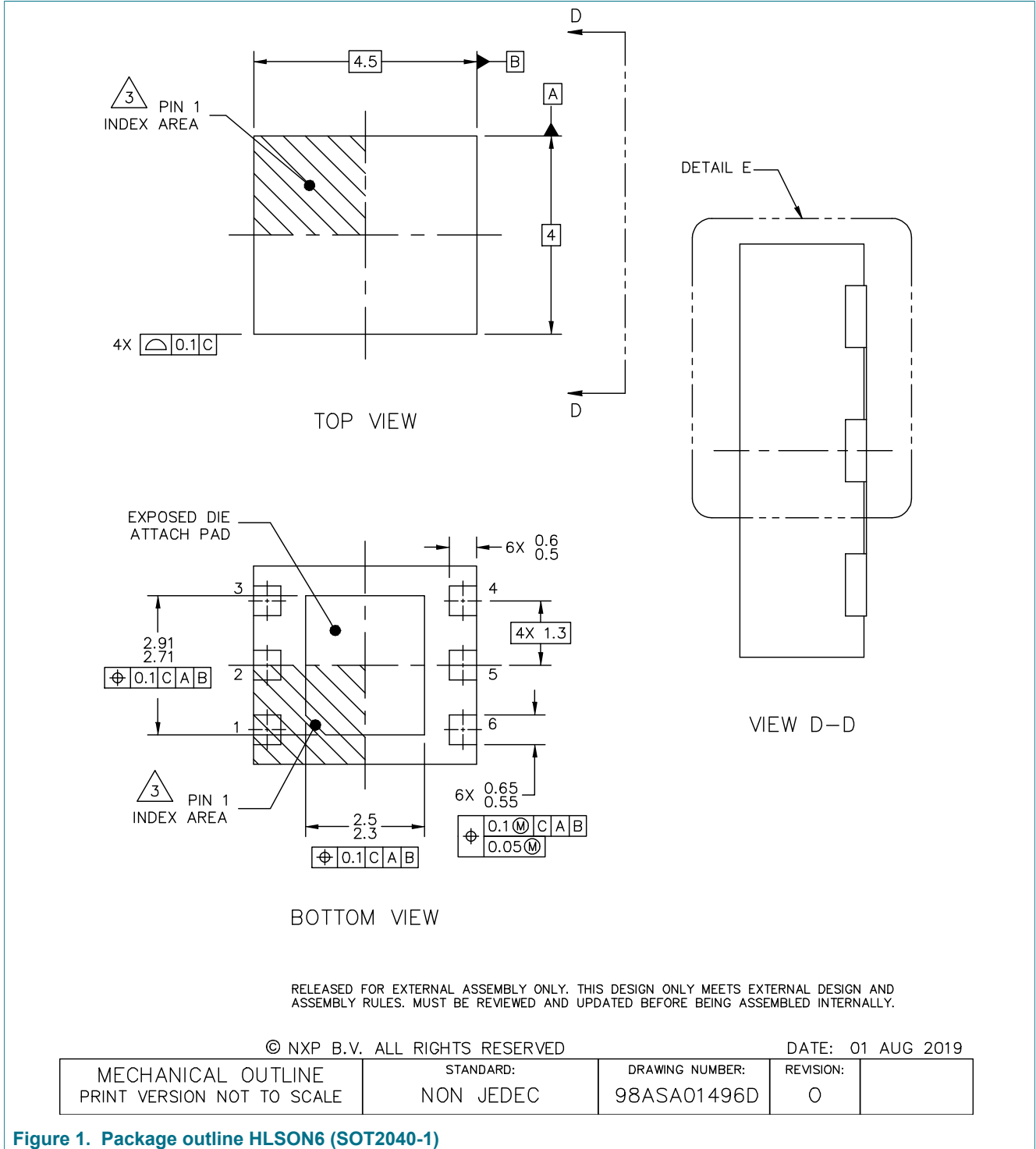


Figure 1. Package outline HLSO6 (SOT2040-1)

HLSON6, thermal enhanced low profile small outline package, no leads, 6 terminals, 1.3 mm pitch, 4.5 mm x 4.0 mm x 1.2 mm body

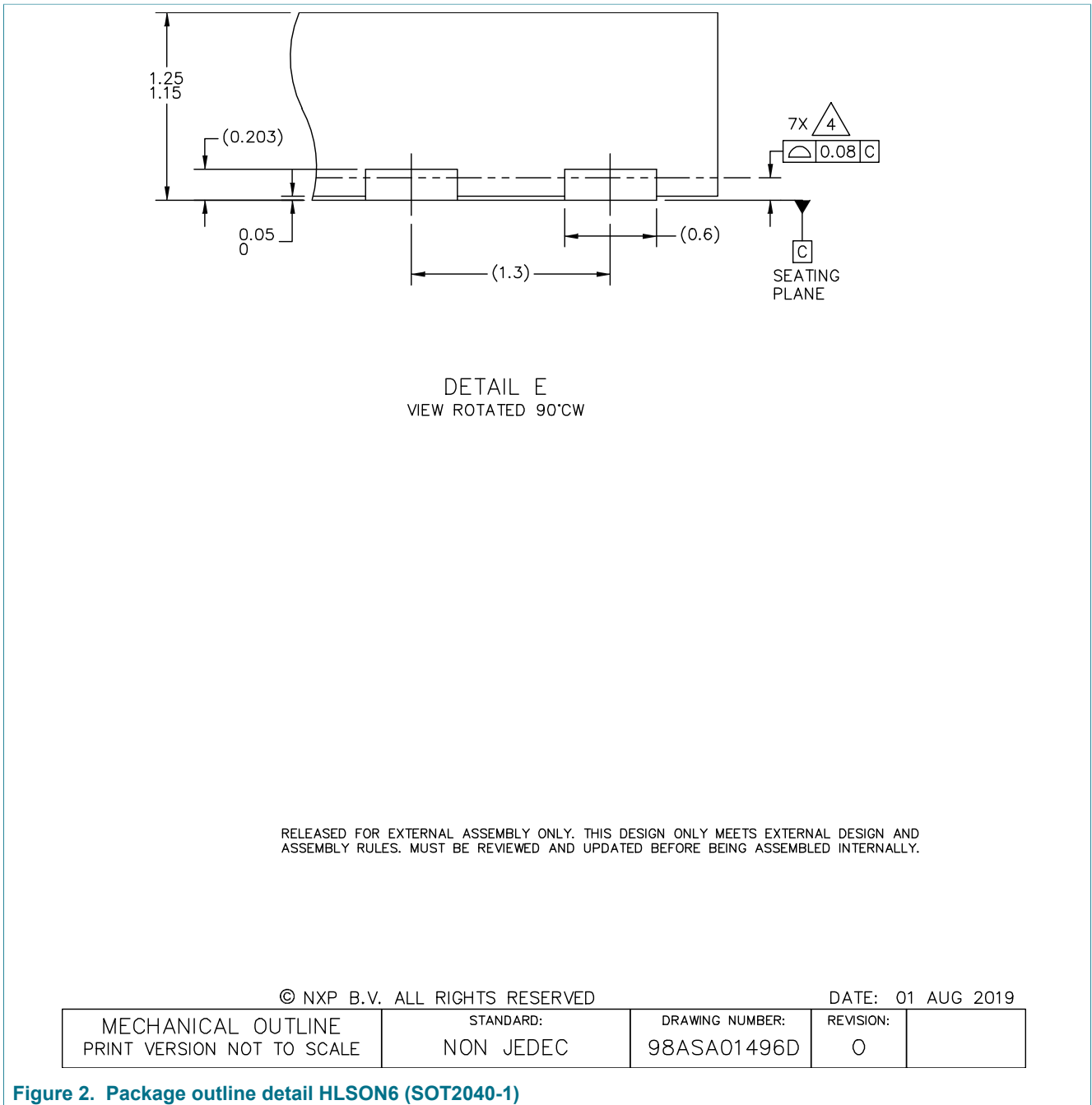


Figure 2. Package outline detail HLSON6 (SOT2040-1)

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3 Soldering

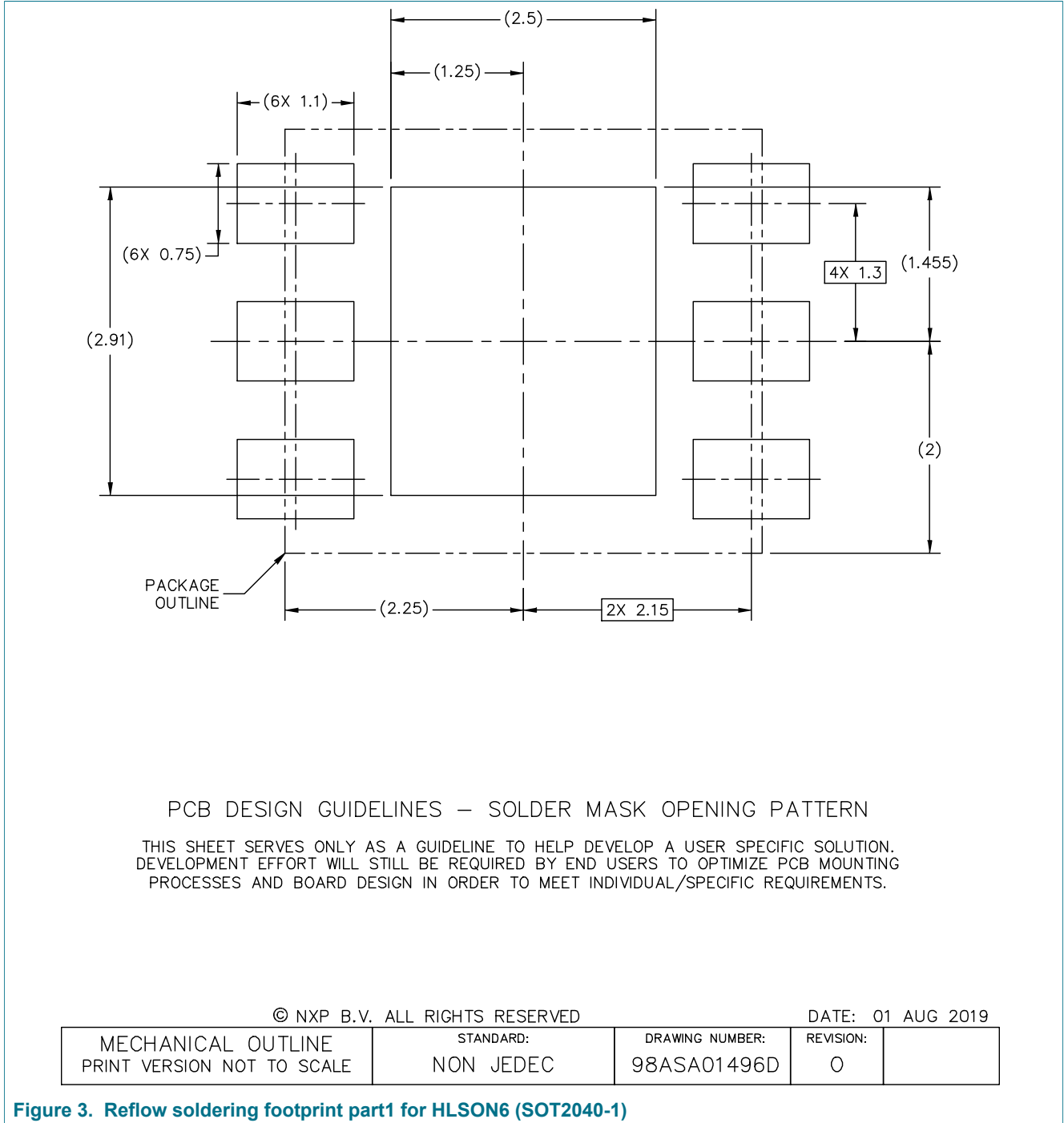
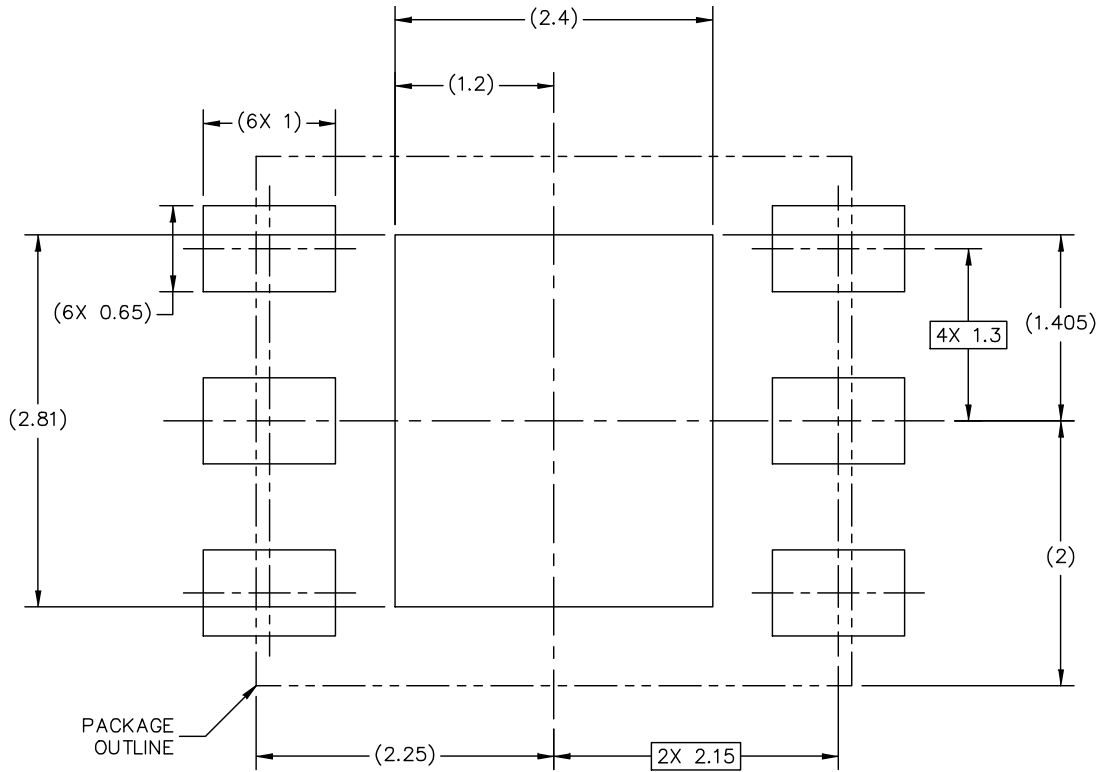


Figure 3. Reflow soldering footprint part1 for HLSON6 (SOT2040-1)

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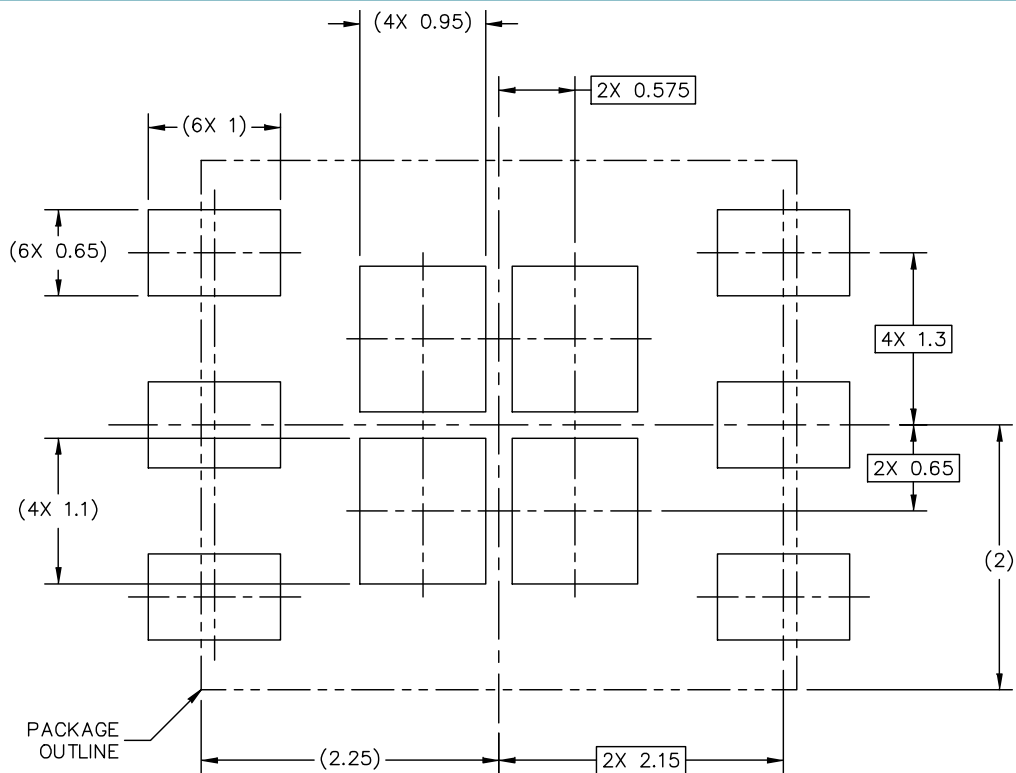
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Figure 4. Reflow soldering footprint part2 for HLSON6 (SOT2040-1)

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RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HLSON6 (SOT2040-1)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.

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Figure 6. Package outline note HLSON6 (SOT2040-1)

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